

Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 292873US41PCT	SERIAL NO. 10/584,052	
LIST OF REFERENCES CITED BY APPLICANT		APPLICANT Stephane POCAS, et al.				
		FILING DATE June 22, 2006		GROUP 2892		
U.S. PATENT DOCUMENTS						
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS
/E.J./	AA	6,340,812	01/22/02	Yoshihiro IZUMI, et al		
	AB	2004/0097008 A1	05/2004	Glen J. LEEDY		
	AC	5,374,564	12/20/94	Michael BRUEL		
	AD	6,281,039	08/28/01	MARION		
	AE	2004/0014299	01/22/04	Hubert MORICEAU, et al.		
	AF	5,880,010	03/1999	Davison, HOWARD L.		
	AG	6,097,096	08/2000	GARDNER, et al.		
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	AN	2002/0173118	11/2002	DIETRICH, et al.		
FOREIGN PATENT DOCUMENTS						
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO	
/E.J./	AO	2 783 969	03/31/00	France (equivalent of US 6, 281, 039)		X
	AP	2 816 445	05/10/02	France (equivalent of US 2004/0014299)		X
	AQ	WO/2003/028101	04/2003	France (equivalent of US 2005/0020029)		X
	AR	WO/01/18853 A1	03/2001	World Intellect (equivalent of US 7,208,392)		X
	AS					
	AT					
	AU					
	AV					
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)						
/E.J./	AW	Q.-Y. TONG, et al., "SEMICONDUCTOR WAFER BONDING: SCIENCE AND TECHNOLOGY", JOHN WILEY & SONS, INC., XP 008042464, pages 215-219, 1999.				
	AX	Goran THUNGSTROM, et al., "CONTACTS TO MONOCRYSTALLINE N - AND P- TYPE SILICON BY WAFER BONDING USING COBALT DISILICIDE", Physica Scripta, Vol. T54, 1994, pages 77-80.				
	AY	ISMAIL, M.S., et al., "PLATINUM SILICIDE FUSION BONDING", Electronics Letters, Vo. 27, No. 13, pages 1153-1155, 1991.				
	AZ	PLOESSL, A., et al., "WAFER DIRECT BONDING: TAILORING ADHESION BETWEEN BRITTLE MATERIALS", Materials Science and Engineering, Vol. 25, No. 1-2, pages 1-88, 1999.			<input checked="" type="checkbox"/> Additional References sheet(s) attached	
Examiner	/Eric Jones/			Date Considered	01/21/2011	
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.						

SHEET 2 OF 2

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				FILING DATE June 22, 2006		GROUP 2892	
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
/E.J./	BA	2003/0129780	07/2003	Andre AUBERTON-HERVE			
	BB	2005/0020029	01/2005	JEAN-SEBASTIEN, Danel			
	BC	2005/0104089	05/2005	ENGELMANN, et al.			
	BD	7,208,392 B1	04/2007	JAUSSAUD, et al.			
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	BF	2008/0041517	02/21/08	Hubert MORICEAU, et al.			
	BG	2008/0296712	12/04/08	Guy FEUILLET, et al.			
	BH						
	BI						
	BJ						
	BK						
	BL						
	BM						
	BN						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION		
					YES	NO	
	BO						
	BP						
	BQ						
	BR						
	BS						
	BT						
	BU						
	BV						
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
/E.J./	BW	SHIGETOU, A., et al., "ROOM TEMPERATURE BONDING OF ULTRA-FINE PITCH AND LOW-PROFILED CU ELECTRODES FOR BUMP-LESS INTERCONNECT", Electronic Components and Technology Conference, Vol. 53, pages 848-852, 2003.					
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/E.J./	BY	B. ASPAR, et al., "SMART-CUT PROCESS USING METALLIC BONDING: APPLICATION TO TRANSFER OF Si, GaAs, InP THIN FILMS", Electronics Letters, Vol. 35, No. 12, June 10, 1999, pages 1024-1025.					
	BZ					<input type="checkbox"/> Additional References sheet(s) attached	
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